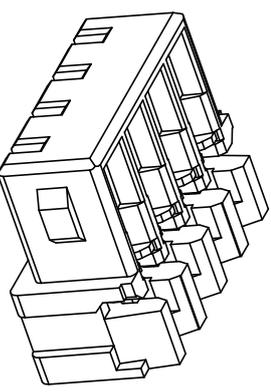
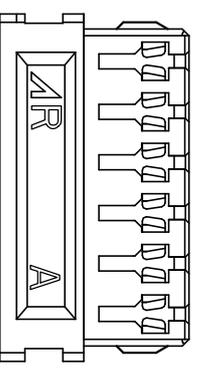
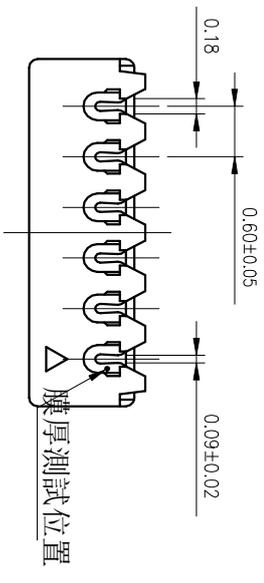
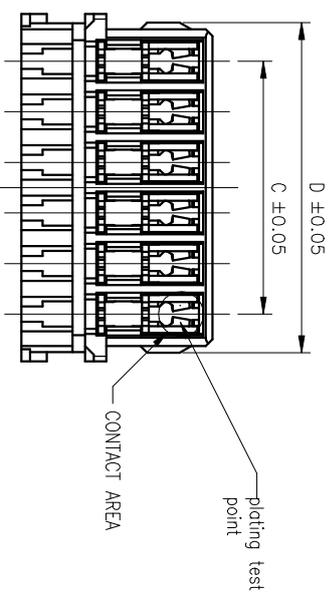
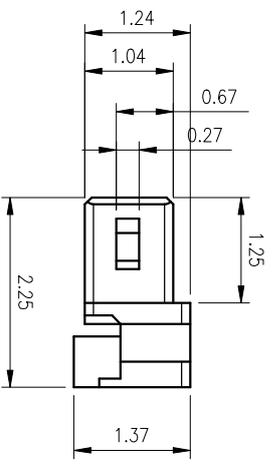
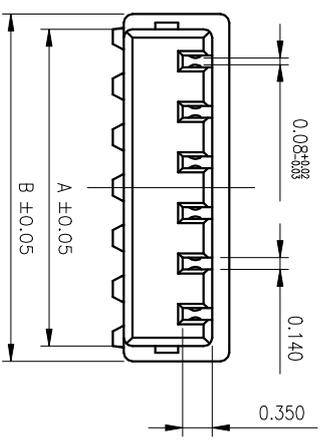
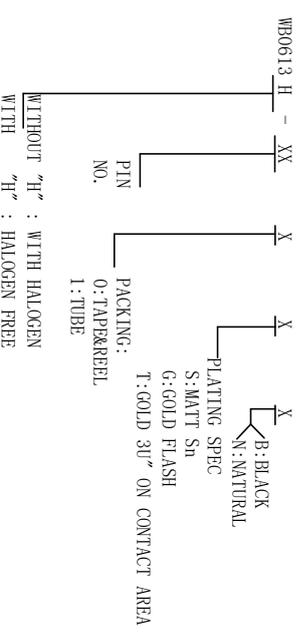


REV.	ECN NO.	DESCRIPTION	DATE	DESIGN
D		调整电气性能描述更新图框	2021.10.18	XUETA09UO

NOTE:
 1. MATERIAL: SEE BOM
 2. FINISH: CONTACT: 50U"MIN,NICKEL UNDERPLATING OVERALL. SURFACE FOLLOW THE P/N.

3. SPEC. PLS. REFER TO EIO002:
 DIM. MARKED \otimes SHOULD BE MEASURED BY FAI;
 DIM. MARKED ∇ SHOULD BE CONTROLLED BY QC;
 DIM. MARKED \square SHOULD BE MEASURED TERMLY BY QC;
 DIM. MARKED \square SHOULD BE ANALYSED TERMLY BY QC;

4. ORDERING INFORMATION:



CIRCUITS	DIMENSION			
	A	B	C	D
4	2.56	2.92	1.80	2.72
6	3.76	4.12	3.00	3.92

2	TERMINAL	~	Copper Alloy
1	HOUSING	1	THERMALPLASTIC,UL94-V0 NATURAL
NO.	DESCRIPTION	Q'TY.	MATERIAL

一般公差 X: ± 0.5 .XX ± 0.15 .X ± 0.25 .XXX ± 0.10 ANGLES $\pm 2^\circ$		品名 (TITLE) 0.6 MM PITCH WTB CONN	
檢驗尺寸標示 SYMBOLS \otimes INDICATE CLASSIFICATION DIMENSION MARK IS CRITICAL DIM. MARK IS MAJOR DIM.		圖號 (PNG NO.) C-WB0613H-XXXXX	
表面處理 (FINISH)		製圖 (DR) XUETA09UO	
比例 (SCALE) 1:1		審核 (CHK) LEO-HE	
單位 (UNITS) mm		核准 (APPD) LEO-HE	
張數 (SHEET) 1/1		尺寸 (SIZE) A4	
REV D		日期 (DATE) 2021.10.18	

希尔盛精密电子(昆山)有限公司